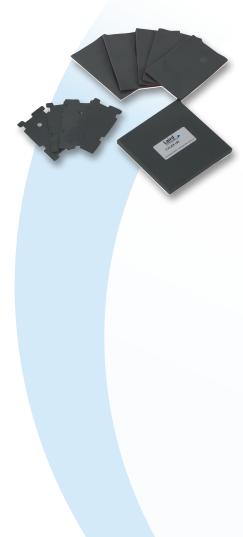


Innovative Technology

for a **Connected** World

Tflex[™] 500 Series Thermal Gap Filler



COMPLIANT 2.8 W/mK THERMALLY CONDUCTIVE GAP FILLER

Tflex[™] 500 is a compliant elastomer gap filler designed to provide excellent thermal performance while remaining cost effective. This soft interface pad conforms well with minimal pressure, resulting in little or no stress on mating parts. Tflex[™] 500's unique silicone and filler combination has extremely low silicone extractables compared to many other silicone interface products. Tflex[™] 500 meets NASA outgassing specification.

Tflex[™] 500 is naturally tacky, no adhesive coating is required. Tflex[™] 500 is electrically insulating, stable from -50°C to 200°C and is certified to UL 94V0 flammability rating.

FEATURES AND BENEFITS

- Thermal conductivity 2.8 W/mK
- Highly compliant and cost effective
- Low thermal resistance even at low pressure
- Available in thicknesses from 0.020-inch (0.25mm) through 0.200-inch (5.0mm) in 0.010-inch increments
- Naturally tacky for easy assembly
- Low silicone extractables

APPLICATIONS

- Cooling components to chassis
- Telecommunication hardware
- Thermal module for notebook computer
- LED solid state lighting
- Power electronics
- Computer servers
- Graphics cards
- Gaming systems
- LCD and PDP flat panel displays
- Industrial automation equipment
- Wireless infrastructure
- Fragile ASIC components
- Automotive engine control
- IT devices
- Military electronics

global solutions: local support...

Americas: +1.800.843.4556 Europe: +49.8031.2460.0 Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com www.lairdtech.com/thermal

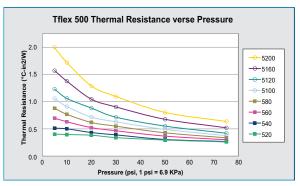


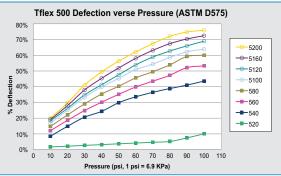
Tflex[™] 500 Series Thermal Gap Filler

Innovative **Technology** for a **Connected** World

Tflex[™] 500 TYPICAL PROPERTIES Thermal Gap Filler Preliminary

| | Tflex™ 500 Preliminary | TEST METHOD |
|--|----------------------------------|----------------------|
| Construction | Filled silicone elastomer | NA |
| Color | Light Blue | Visual |
| Thermal Conductivity | 2.8 W/mK | ASTM D5470 |
| Hardness (Shore 00) | 40 (at 3 second delay) | ASTM D2240 |
| Density | 3.0 g/cc | Helium Pycnometer |
| Standard Thickness Range | 0.020" - 0.200" (0.5 - 5.1mm) | |
| Thickness Tolerance | ±10% | |
| UL Flammability Rating | 94 V0 | UL |
| Temperature Range | -50°C to 200°C | NA |
| Volume Resistivity | 10^13 ohm-cm | ASTM D257 |
| Outgassing TML | 0.29% | ASTM E595 |
| Outgassing CVCM | 0.04% | ASTM E595 |
| Coefficient Thermal Expansion (CTE) | 37.4 ppm/°C 70°C-130°C | IPC-TM-650 2.4.24 |





STANDARD THICKNESSES

0.020 to 0.200-inch (0.25 to 5.0mm).

0.020 to 0.030-inch (0.5 to 0.76mm) thick material come standard with fiberglass reinforcement. 0.020 through 0.200 thick material available in 0.010-inch (0.25mm) increments.

OPTIONS

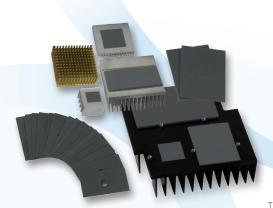
Proprietary DC1 option available to eliminate tack from top side to aid in handling.

MATERIAL NAME AND THICKNESS

Tflex[™] indicates Laird Technologies' brand thermally conductive elastomeric gap filler product. 5xxx indicates '500 series' 2.8 W/mK material, and xxx indicates thickness in -mil (0.001-inches); -DC1 designates proprietary tack eliminating option

Examples:

Tflex[™] 5120 = 0.120-inch thick material Tflex[™] 5120-DC1 = 0.0120-inch thick material with proprietary DC1 option



THR-DS-Tflex-500 0110

Any information furnished by Laird Technologies and its agents is believed to be accurate and reliable. Responsibility for the use and application of Laird Technologies materials rests with the end user since Laird Technologies materials or products for any specific or general uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall no the laible for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies consets: terms and conditions of sale in effect from time to time, a copy of which will be trunished upon request. Jamages of the formologies for ducts are sold pursuant to the Laird Technologies' domestic terms and conditions of sale in effect from time to time, a copy of which will be furnished upon request. Document A15958-00 Rev B, 11/2009.

© 2010 All Rights Reserved. Laird Technologies is a registered trademark of Laird Technologies, Inc.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Thermal Interface Products category:

Click to view products by Laird Connectivity manufacturer:

Other Similar products are found below :

 7721-9PPS
 FGN80-2
 PFM-172-60
 A-40
 174-9-230P
 9601-7
 5300AC 1.500G
 08133
 V6622C
 TVQF-1225-07S
 TP0001
 4860
 SC80-W2

 V6516C
 A17536-04
 A17713-06
 A17713-05
 A17653-05
 A17690-06
 A17775-03
 A17690-05
 A17653-02
 A17689-02
 A17690-04
 A17775-06

 05
 A17775-06
 A17690-08
 A17690-02
 A17653-06
 A17690-12
 A17653-03
 A17536-02
 A17689-03
 A17536-10
 A17752-13

 A17752-04
 A17752-07
 A17634-12
 19-36565-0001-1
 A17752-09
 22000-001A
 A17752-20
 A17752-16
 A17752-12
 A17653-04
 A17634-10

 A17634-09
 A17634-07
 A17633-20
 A17633-20
 A17633-20
 A17633-20
 A17634-07